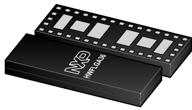


SOT1948-1

HWFLGA36, plastic thermal enhanced very very thin fine-pitch land grid array package, 0.4 mm pitch, 2.1 mm x 6 mm x 0.637 mm body

23 January 2020 Package information

1 Package summary

Terminal position code	B (bottom)
Package type descriptive code	HWFLGA36
Package style descriptive code	FLGA (fine-pitch land grid array package)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	14-11-2019
Manufacturer package code	98ASA01139D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	2.05	2.1	2.15	mm
package width	5.95	6	6.05	mm
package height	0.597	0.637	0.677	mm
nominal pitch	-	0.4	-	mm
actual quantity of termination	-	36	-	

2 Package outline

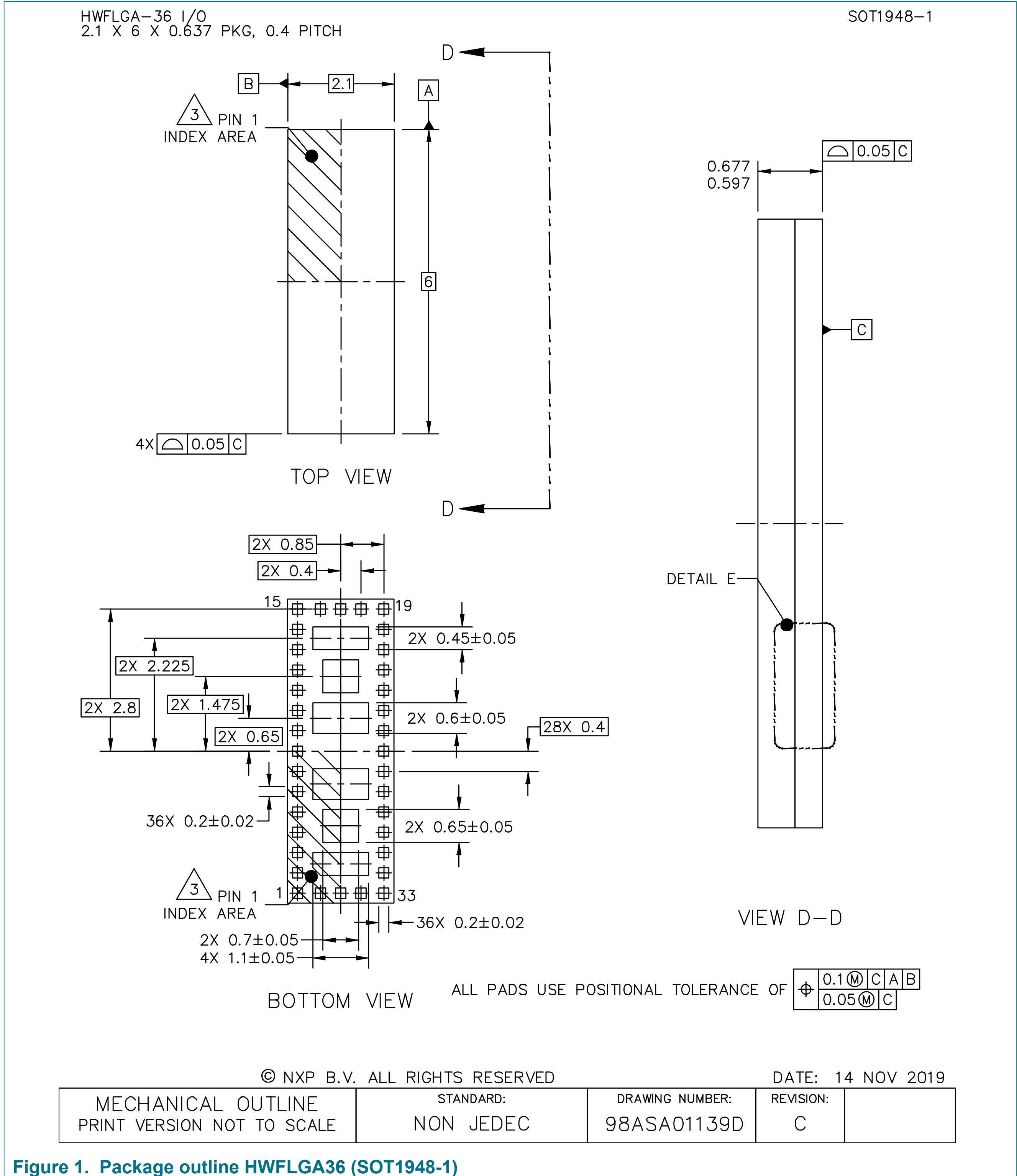
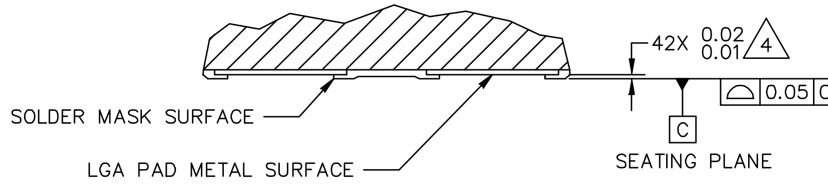


Figure 1. Package outline HWFLGA36 (SOT1948-1)

© NXP B.V. 2020. All rights reserved.

HWFLGA-36 I/O
2.1 X 6 X 0.637 PKG, 0.4 PITCH

SOT1948-1



DETAIL E
VIEW ROTATED 90° CW

© NXP B.V. ALL RIGHTS RESERVED

DATE: 14 NOV 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01139D	REVISION: C	

Figure 2. Package outline dt HWFLGA36 (SOT1948-1)

© NXP B.V. 2020. All rights reserved.

3 Soldering

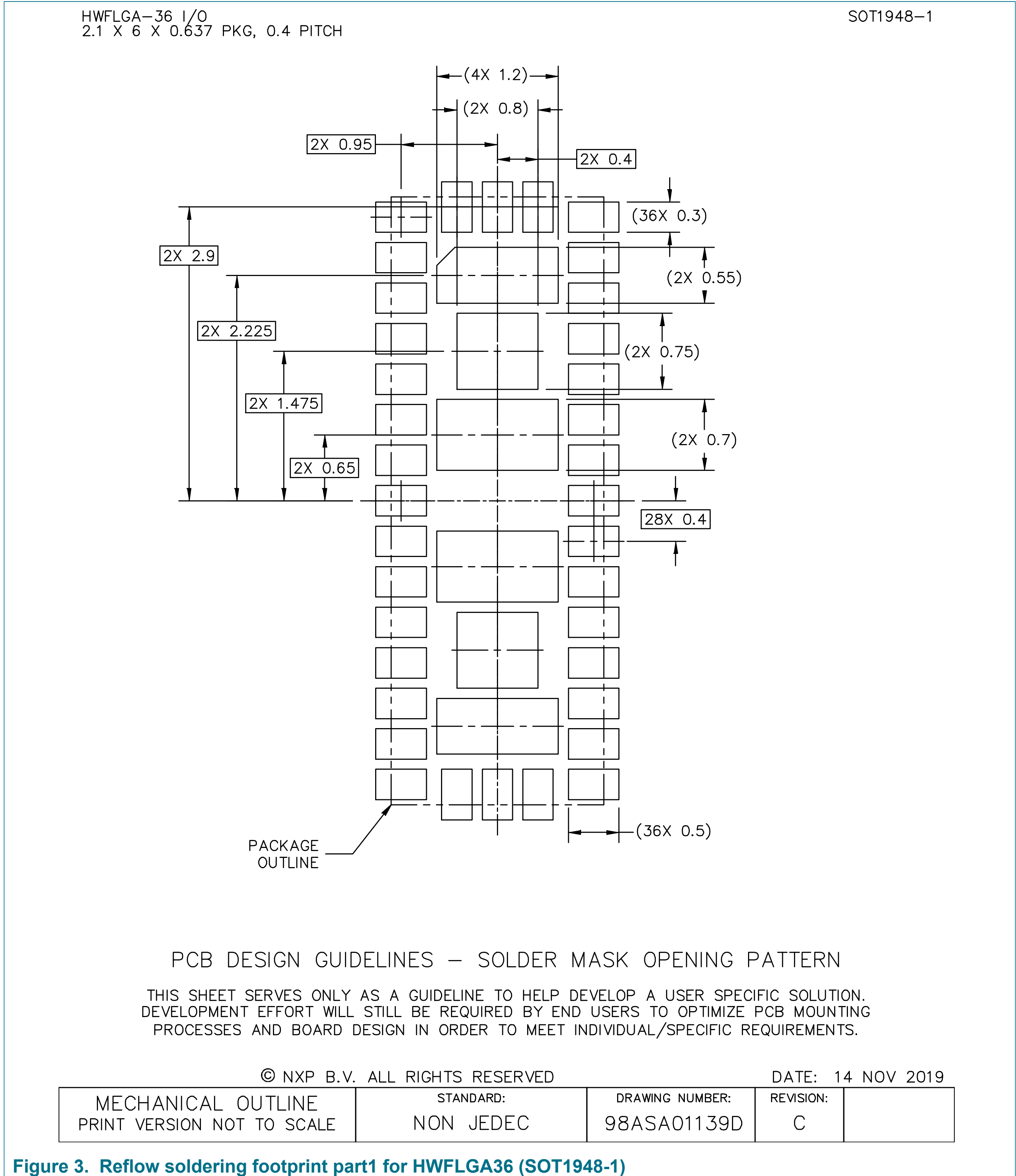


Figure 3. Reflow soldering footprint part1 for HWFLGA36 (SOT1948-1)

All information provided in this document is subject to legal disclaimers.

© NXP B.V. 2020. All rights reserved.

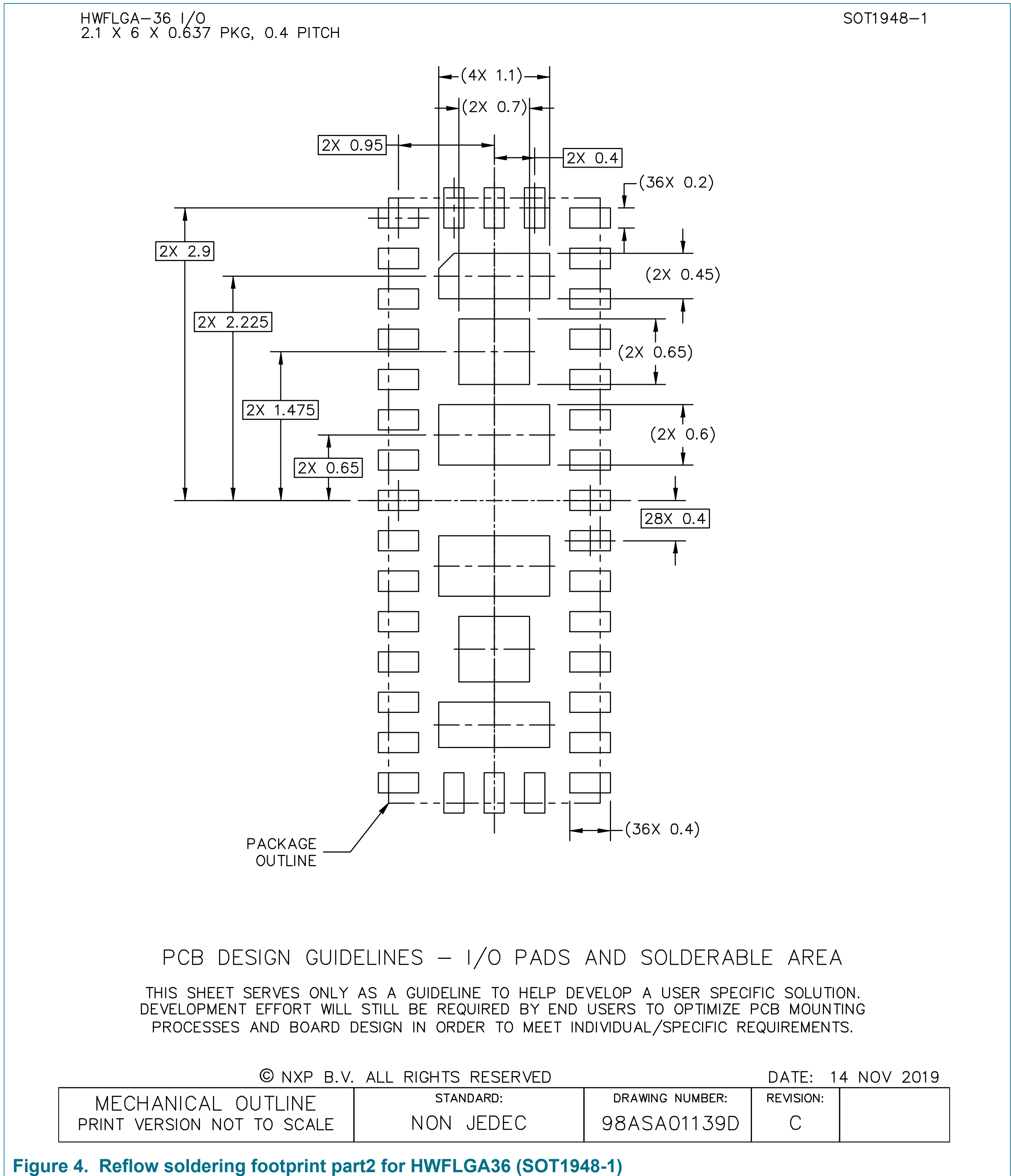


Figure 4. Reflow soldering footprint part2 for HWFLGA36 (SOT1948-1)

All information provided in this document is subject to legal disclaimers.

© NXP B.V. 2020. All rights reserved.

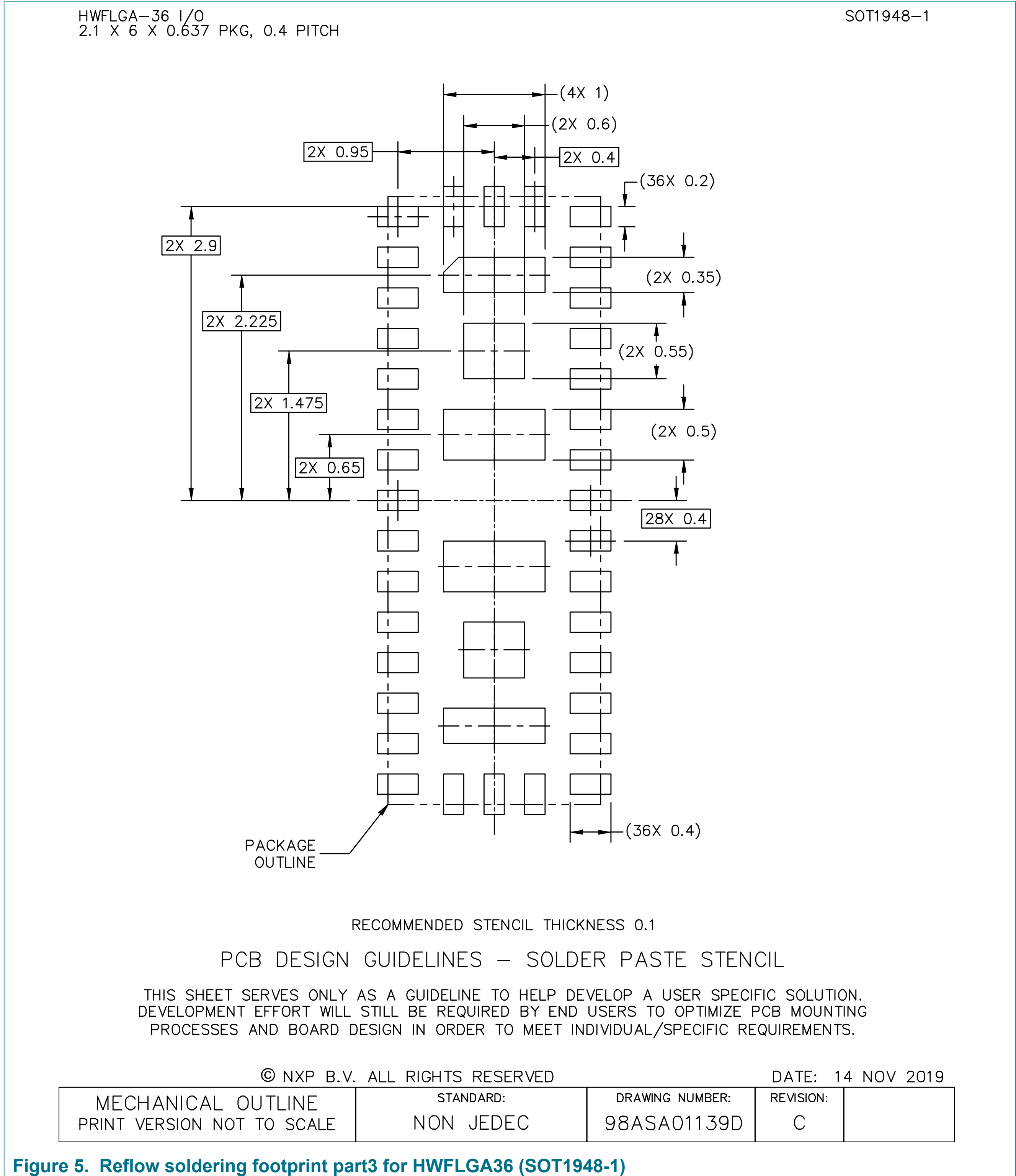


Figure 5. Reflow soldering footprint part3 for HWFLGA36 (SOT1948-1)

All information provided in this document is subject to legal disclaimers.

© NXP B.V. 2020. All rights reserved.

HWFLGA-36 I/O
2.1 X 6 X 0.637 PKG, 0.4 PITCH

SOT1948-1

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 CONFIGURATION MAY VARY.
4. DIMENSION APPLIES TO ALL LEADS.

© NXP B.V. ALL RIGHTS RESERVED

DATE: 14 NOV 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01139D	REVISION: C	

Figure 6. Package outline note HWFLGA36 (SOT1948-1)

All information provided in this document is subject to legal disclaimers.

© NXP B.V. 2020. All rights reserved.

4 Legal information

Disclaimers

Limited warranty and liability — Information in this document is believed to be accurate and reliable. However, NXP Semiconductors does not give any representations or warranties, expressed or implied, as to the accuracy or completeness of such information and shall have no liability for the consequences of use of such information. NXP Semiconductors takes no responsibility for the content in this document if provided by an information source outside of NXP Semiconductors.

In no event shall NXP Semiconductors be liable for any indirect, incidental, punitive, special or consequential damages (including - without limitation - lost profits, lost savings, business interruption, costs related to the removal or replacement of any products or rework charges) whether or not such damages are based on tort (including negligence), warranty, breach of contract or any other legal theory.

Notwithstanding any damages that customer might incur for any reason whatsoever, NXP Semiconductors' aggregate and cumulative liability towards customer for the products described herein shall be limited in accordance with the Terms and conditions of commercial sale of NXP Semiconductors.

Right to make changes — NXP Semiconductors reserves the right to make changes to information published in this document, including without limitation specifications and product descriptions, at any time and without notice. This document supersedes and replaces all information supplied prior to the publication hereof.

All information provided in this document is subject to legal disclaimers.

© NXP B.V. 2020. All rights reserved.

Contents

1 Package summary 1
2 Package outline 2
3 Soldering 4
4 Legal information 8

© NXP B.V. 2020. All rights reserved.

For more information, please visit: http://www.nxp.com
For sales office addresses, please send an email to: salesaddresses@nxp.com

Date of release: 23 January 2020